

ABSTRACT OF THE DISCLOSURE

A tape ball grid array package and a method of fabricating the package. A dielectric tape having a metallic layer on both sides is provided. The metallic layers are patterned to form circuits. A plurality of via holes is formed in the dielectric tape. The via holes pass through the lower metallic layer and the tape dielectric but stop at the upper metallic layer, thereby forming a plurality of blind holes. A solder mask layer is formed over each side of the tape and the solder mask layers are patterned to expose a portion of the metallic layer serving as contact points for connecting with a chip. A solder ball is inserted into each blind hole. One end of the solder ball protrudes from the surface of the solder mask layer. Wire-bonding operation or flip-chip assembly process is conducted to form electrical connection between the chip and the contact points.